

to use an inexpensive resin substrate instead of an expensive ceramics substrate.

#### BRIEF DESCRIPTION OF THE DRAWINGS

In the accompanying drawings:

Fig. 1 is a sectional side elevation illustrating a schematic structure of a first embodiment of a semiconductor device according to the present invention;

Fig. 2A and <sup>2</sup>B are perspective views of the semiconductor device shown in Fig. 1 for explaining the structure thereof, and particularly, for explaining the rear surface side of a semiconductor package, and Fig. 2C is a perspective view of the semiconductor device shown in Fig. 1 for explaining the structure thereof, and particularly, for explaining the front surface side of the semiconductor package;

Fig. 3 is a perspective view of a semiconductor <sup>chip</sup>element illustrating a surface where the element is formed;

Fig. 4 is a perspective view of the semiconductor device for explaining the rear surface side thereof;

Fig. 5 is a perspective view of the semiconductor device for explaining the rear surface side thereof;

Fig. 6 is a sectional side elevation illustrating a schematic structure of a second embodiment of a semiconductor